2SC4621

Silicon NPN triple diffusion planar type

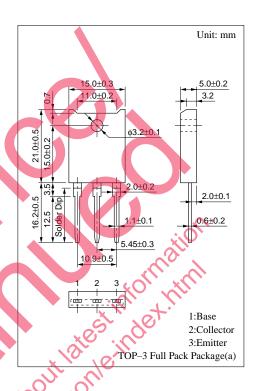
For high breakdown voltage high-speed switching

Features

- High-speed switching
- ullet High collector to base voltage V_{CBO}
- Wide area of safe operation (ASO)
- Full-pack package which can be installed to the heat sink with one screw

Absolute Maximum Ratings (T_C=25°C)

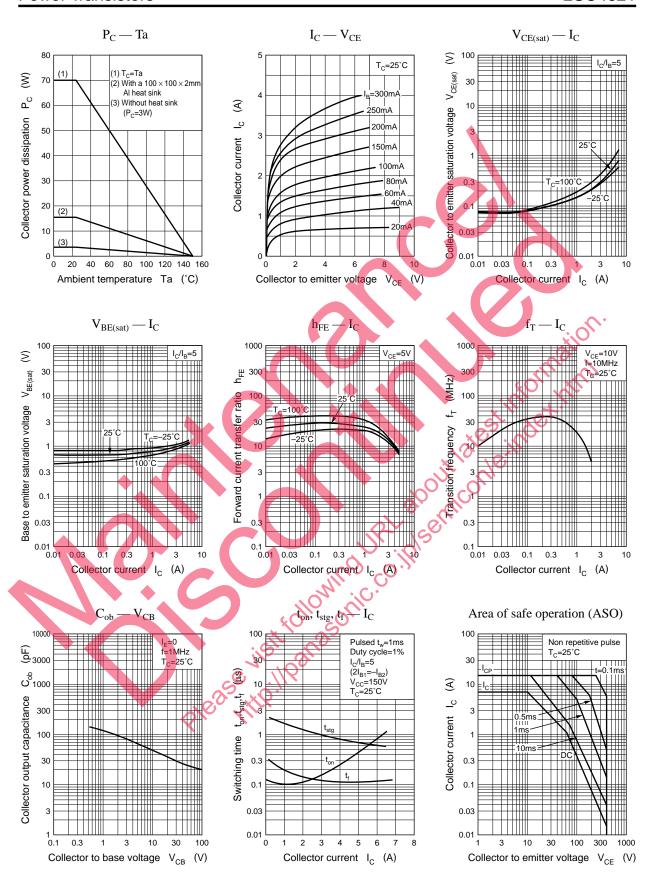
Parameter	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	500	V
C-11	V _{CES}	500	V
Collector to emitter voltage	V _{CEO}	400	V
Emitter to base voltage	Emitter to base voltage V _{EBO}		V
Peak collector current			A
Collector current	$I_{\mathbb{C}}$	7	A
Base current	I_{B}	3 A	
Collector power T _C =25°C	D	70	W
dissipation Ta=25°C	P_{C}	3.0	, vv
Junction temperature	T_{j}	150	°C
Storage temperature	T_{stg}	-55 to +150	.c.O
			117



Electrical Characteristics (T_C=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = 500V, I_{E} = 0$			100	μΑ
Emitter cutoff current	I _{EBO}	$V_{EB} = 5V, I_C = 0$			100	μА
Collector to emitter voltage	V _{CEO}	$I_{\rm C} = 10$ mA, $I_{\rm B} = 0$	400			V
Forward current transfer ratio	h _{FE1}	$V_{CE} = 5V, I_{C} = 0.1A$	15			
	h _{FE2}	$V_{CE} = 5V, I_{C} = 3A$	8			
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 3A, I_B = 0.6A$			1	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_C = 3A, I_B = 0.6A$			1.5	V
Transition frequency	f_{T}	$V_{CE} = 10V, I_{C} = 0.5A, f = 10MHz$		30		MHz
Turn-on time	t _{on}	$I_C = 3A, I_{B1} = 0.6A, I_{B2} = -1.2A,$ $V_{CC} = 150V$			0.7	μs
Storage time	t _{stg}				2	μs
Fall time	t _f				0.3	μs

Power Transistors 2SC4621



2 Panasonic

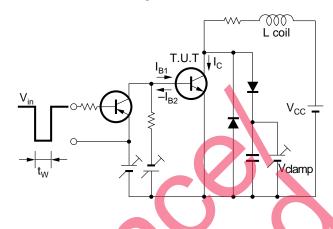
Power Transistors 2SC4621

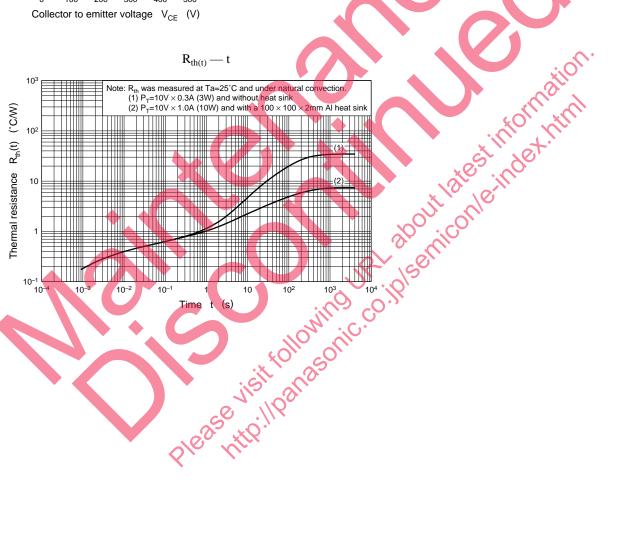
Area of safe operation, reverse bias ASO

L_{coil} =200 μ H I_{C}/I_{B} =5 $(I_{B1}$ = $-I_{B2}$) T_{C} =25 $^{\circ}$ C 14 3 12 Collector current I_c 100 200 300 400

Collector to emitter voltage V_{CE} (V)

Reverse bias ASO measuring circuit





Panasonic 3

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